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**Part Number:** [73659-0003](#)  
**Status:** **Active**  
**Overview:** HDM®  
**Description:** 2.00mm Pitch HDM® Board-to-Board Backplane Power Module, Vertical, SMC, Power Receptacle, 12 Circuits, Gold (Au) 0.76µm

**Documents:**

[3D Model](#) [RoHS Certificate of Compliance \(PDF\)](#)  
[Drawing \(PDF\)](#)

**Agency Certification**

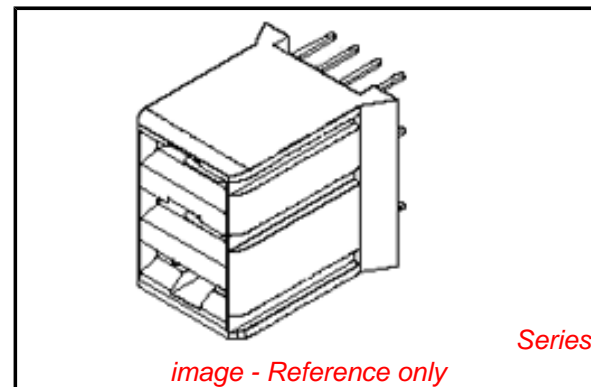
CSA LR19980  
 UL E29179

**General**

Product Family Backplane Connectors  
 Series [73659](#)  
 Application Backplane  
 Comments Midplane Power Module  
 Component Type Power Header  
 Overview [HDM®](#)  
 Product Name HDM®  
 Style N/A

**Physical**

Circuits (Loaded) 12  
 Circuits (maximum) 12  
 Color - Resin Black  
 Durability (mating cycles max) 250  
 First Mate / Last Break No  
 Flammability 94V-0  
 Guide to Mating Part No  
 Keying to Mating Part None  
 Material - Metal Beryllium Copper  
 Material - Plating Mating Gold  
 Material - Plating Termination Tin  
 Material - Resin High Temperature Thermoplastic  
 Number of Columns 1  
 Number of Pairs Open Pin Field  
 Number of Rows 3  
 Orientation Vertical  
 PC Tail Length 3.00mm  
 PCB Locator No  
 PCB Retention Yes  
 PCB Thickness - Recommended 2.50mm  
 Packaging Type Tube  
 Pitch - Mating Interface 2.00mm  
 Pitch - Termination Interface 2.00mm  
 Plating min - Mating 0.762µm  
 Plating min - Termination 3.810µm  
 Polarized to PCB No  
 Stackable No  
 Surface Mount Compatible (SMC) Yes  
 Temperature Range - Operating -55°C to +105°C  
 Termination Interface: Style Through Hole



**EU RoHS**

**ELV and RoHS Compliant**  
**REACH SVHC Contains SVHC: No**  
**Low-Halogen Status Low-Halogen**

**China RoHS**



**Need more information on product environmental compliance?**

Email [productcompliance@molex.com](mailto:productcompliance@molex.com)  
 For a multiple part number RoHS Certificate of Compliance, [click here](#)

Please visit the [Contact Us](#) section for any non-product compliance questions.

**Search Parts in this Series**

[73659Series](#)

**Mates With**

[73651 HDM® Board-to-Board Daughterboard Power Module](#)

**Electrical**

|                               |          |
|-------------------------------|----------|
| Current - Maximum per Contact | 15A      |
| Data Rate                     | 1.0 Gbps |
| Real Signals (per 25mm)       | 38       |
| Shielded                      | Yes      |
| Voltage - Maximum             | 500V AC  |

**Solder Process Data**

|                              |                           |
|------------------------------|---------------------------|
| Lead-free Process Capability | Reflow Capable (SMT only) |
| Process Temperature max. C   | 260                       |

**Material Info****Reference - Drawing Numbers**

|               |                |
|---------------|----------------|
| Sales Drawing | SDA-73659-000* |
|---------------|----------------|

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